

Product Information

Adhesive System

Constructional

Moisture cure

Bectron[®] AR 4826 N

ELANTAS Beck GmbH

Grossmannstr. 105

20539 Hamburg

Germany

Tel +49 40 78946 0

Fax +49 40 78946 276

bectron.elantas.beck@altana.com

www.elantas.com

Product description

Bectron® AR 4826 N is a 1-component solvent free resin based on polyurethane with thixotropic rheology and fast cure by accelerated reaction with moisture in the atmosphere to form a flexible material suitable for sealing and protection of components and connections on the PCB.

Bectron® AR 4826 N satisfies the requirements of ROHS.

Areas of application

Bectron® AR 4826 N is used for chemical protection of PCBs against moisture and contamination and for securing large components on the board against mechanical shock and vibration. It is an effective adhesive on most surfaces of PCBs and electronic components. It has thixotropic flow characteristics suitable for thick film coating selectively and accurately covering individual components sealing open connections on the PCB. Via holes in PCBs can be covered.

The applied material will remain in place during curing with no stress on delicate components protected.

The cured product is flexible and will not damage sensitive components under thermal shock, including low temperatures.

Properties of the cured material

Good electrical properties even after water immersion.

Rapid curing

Thixotropic

Good adhesion on many substrates

Low shrinkage on curing

Withstands low temperature (-50°C)

Resistant to moisture and migration

Resistant to organic and inorganic solvents

Solvent Free

Storage

Bectron® AR 4826 N is supplied in sealed cartridges which can be stored for 12 weeks between 5 and 10 °C. Freezing at -18°C will give long shelf life without risk to the material.

Processing suggestions

Bectron® AR 4826 N should be applied directly from the cartridge with a suitable nozzle. If the AR 4826 N is transferred to a second cartridge or applicator it must be used in a short time as exposure to moisture will start the curing reaction. Excessive exposure to moisture will cause increase in viscosity and prevent controlled application.

The cartridges should be allowed to reach their application temperature, 25 to 30 °C, before use to allow the viscosity to reach the specified level.

Curing at room temperature at ≥ 50 % relative humidity allows 1 – 2 hour process time and 24 hours for thorough curing up to 0.5 mm. Complete curing may require up to 2 weeks depending on the conditions.

Increased temperature and humidity can reduce the curing time.

Heating in a conventional oven with low humidity is not suitable for curing.

For optimal adhesion, curing of 24 hours @ RT, afterwards 24 hours @ 90°C.

To ensure satisfactory adhesion on the PCB surface the following should be checked:

- Use of residue-free flux
- ensure dry surfaces
- Check compatibility of the coating resin with the solder resist and solder paste.

Table 1 - Properties of materials as supplied

AR 4826 N

Property	Condition	Value	Unit
Colour		blue transparent	
Viscosity DIN 53018	23°C	Thixotropic	mPa.s
Density DIN 53217	23°C	1.1 ± 0.05	g/cm ³
Shelf Life	5 -10 °C	12	weeks

Table 2 – Thermal Properties of cured compound

Property	Condition	Value	Unit
Temperature Range		-50 to +120	°C

Table 3 - Mechanical properties of cured compound

Property	Condition	Value	Unit
Density DIN 16945	23°C	1.10 ± 0.05	g/cm ³
Hardness DIN 53505	23°C	67 ± 5	Shore A
Elongation to fracture DIN 53455	23°C	300	%

Table 4 - Dielectric properties of cured compound

Property	Condition	Value	Unit
Volume resistivity ρD VDE 0303 Part 2	23°C	2 x 10 ¹²	Ω • cm
After 7 days water immersion	23°C		Ω • cm
Surface Resistivity R ₀ VDE 0303 Part 3	23°C	1.0 x 10 ¹²	Ω
After 7 days water immersion	23°C		Ω
Dielectric Strength	23°C	100	KV/mm

Table 5 – Chemical Properties of cured compound

Property	Condition	Value	Unit
Water Absorption DIN 53495	7 days		%

Our advice in application technology given verbally, in writing and by testing corresponds to the best of our knowledge and belief, but is intended as information given without obligo, also with respect to any protective rights held by third parties. It does not relieve you from your own responsibility to check the products for their suitability to the purposes and processes intended. The application, usage and processing of the products are beyond our reasonable control and will completely fall into your scope of responsibility. Should there nevertheless be a case of liability from our side, this will be limited to any damage to the value of the merchandise delivered by us. Naturally, we assume responsibility for the unobjectionable quality of our products, as defined in our General Terms and Conditions